

**AMENDMENT UNDER 37 C.F.R. § 1.116**  
U.S. APPLN. NO.: 09/735,892

5. (Amended) A semiconductor wafer processing method, comprising adhering a removable pressure-sensitive adhesive sheet which comprises a pressure-sensitive adhesive layer comprising a pressure-sensitive adhesive comprising a polymer in which the content of low-molecular components having a molecular weight of  $10^5$  or lower is 10% by weight or lower, and the polymer has a weight average molecular weight of 930,000 to 2,100,000, to a front or back surface of the wafer, and processing the wafer.